

ABSTRACT OF THE DISCLOSURE

Methods of using dynamic metrology sampling techniques for identified lots, and a system for performing such methods are disclosed. In one illustrative embodiment, the method comprises identifying at least one wafer to be processed, identifying a process tool in which at least one wafer is to be processed, obtaining enhanced metrology data regarding a process operation to be performed in the identified process tool prior to processing the identified at least one wafer in the identified process tool, and positioning at least one wafer in the identified process tool and performing the process operation thereon.